X3 RoHS Report

编号 No.	日期 Date	版本 Version	作者 Author	变更说明 Description of Change
1	2020/5/20	1.0	Vivian Xu	Initial
2	2020/9/30	2.0	Ning Wang	Update RoHS Report
				0.0



Package : Device : Date : HFC FBGA 15X15 X3ME00IBGTEA 2020/9/30

Bart		MATERIAL (Descrip	tion)				SUBS	TANCE (Ingredient/s	In Material)	
State Stat	Material Name	Tradename			SGS Report No.	Due date of SGS Report		CAS	7	
Decision Particular Parti	Substrate	Substrate Thickness=1.156mm, 8 layers, Substrate Material Type = Green Substrate Core =Hitachi CCL- E700GR Soldermask = Hitachi SR7300GR- B	SDS_ABF_GX92_2 0211105_(Security C).pdf	ABF_GX92code92 R_20210821_ (Security C).pdf				7727-43-7/ 60676-86-0/ 64742-94-5/ 112-15-2/ 103429-90-9/ 108-94-1/		
Substant Name Proc Stock			FOF	PDF		01/14/2021 01/14/2021 01/14/2021 03/27/2021	Core	7440-50-8/ 65997-17-3/ 60676-86-0/	20.96%	0.36900000
Page				E700GR_R2_2021 0114_(Security C).pdf	CE/2020/11802 CE/2020/11803 CE/2020/11808		ABF	7631-86-9/ 25068-38-6/ 9003-36-5/ 64742-94-5/ 108-94-1/ 108-88-3/ 78-93-3/ 91-20-3/ 25551-13-7/	3.45%	0.06075000
Directifs Dire				C).pdf			Plugging	25068-38-6/ 9003-36-5/ 110656-67-2/ 471-34-1	1.31%	0.02301494
								7440-22-4/ 7440-50-8/ Trade secret		
December			PDF	PDF			1,6-Bis(2.3-			
Mode			SDS NAMICS UA	Namics UA28 202	CE/2020/84830		Bisphenol F type liquid			
Carbon Date			28_20210213 (Security C).pdf					trade secret	0.03%	0.00052500
Time	Underfill	UA28					Carbon black	1333-86-4	0.01%	0.00010500
TIM X23-7772-4 S2,3 w 1 52 31 3, 26.774 S13 33 3, 26.774 S13 34 3, 26.7							Silicon dioxide	60676-86-0	0.26%	0.00455000
Marchesiste						. 0	Additives	trade secret	0.01%	0.00021000
## PRODUCTION PROJECT		X23-7772-4	POF			0				
Adhesive SE450 2000 1000 1000 1000 1000 1000 1000 10	TIM		23-7772-		CE/2019/A0325	10/14/2020	of ingredients)			
Adhesive SE4490				(Security C).pdf			Aluminum			
Heat spreader	Adhesive	SE4450	SDS_DOW_SE4450 20211101	DOW SE4450 202	CE/2020/21792	02/13/2021	treated aluminum oxide Dimethyl Siloxane,			
Notice (N) 7440-02-0 5.11% 0.09000000000000000000000000000000000	Heat spreader	Heat spreader	SDS ANK FC 202	PDF	XXX			7440-50-8	46.01%	0.81000000
Solder ball SAC30S 0.39mm SSC SMT care residual sparse sold sp			30513_(Security C).pdf	(Security C).pdf	CE/2020/82879	08/26/2021				
Copper T440-50-8 D.02% D.00040250	Solder ball	SAC305/ 0.35mm	SDS_PMT_Lead- Free Solder Sphere	PMT_Sn96.45Ag3C u0.5Ni0.05 G	KA/2020/21237					
Nickel 7440-02-0 0.00% 0.0004025 Nickel 7440-02-0 0.00% 0.0004025 No.										
HD4100 SDS_HTT_PD_000E_202130										
Nonegulatedingredients 109-17-1 0.01% 0.009128305			SDS_HIT_HD- 4000E 202103	HIT HD4000E 202	CE/2019/C0184		N-Methyl-2-Pyrollidone.	872-50-4	0.01%	0.000171007
Nonregulatedingredients 109-17-1 0.00% 2.70011E-06							Polyamic Acid Ester	67-56-1	0.01%	0.000126305
Die Silicon	porynniue						Nonregulatedingredients	109-17-1	0.00%	2.70011E-06
Die Silicon Eigen Silicon Eigen Silicon Eigen Silicon and Its compounds Tartalum 7440-25-7 0.00152% 0.00002684 Tartalum 7440-25-7 0.00052% 0.00002684 Tartalum 7440-33-6 0.00000268 Tartalum 7440-33-7 0.00015% 0.00000268 Tartalum Transport Transpor	Die	Silicon		TSMC F14B Finished Wafer_CE_2019_C0367.pdf	CE/2019/C0367	12/26/2019				
Die Silicon							Silicon and its			
DBM metalization Ti Titanium Ti SDS Umicore Ti 2020/22 (Security C)							Tantalum Titanium Tungsten Cobalt	7440-32-6 7440-33-7 7440-48-4	0.00008% 0.00015% 0.00004%	0.00000134 0.00000268 0.00000067
UBM metalization Ni		Titanium Ti		Umicore_target_Ti4 N5_20210117	CE/2020/13008	01/17/2021	Titanium Ti	7440-32-6	0.00%	1.75277E-05
UBM metalization Cu			SDS_DOW_Nickel Sulphamate_2 0201102 (Security	DOW_Nickel Sulfamate_202 10710 (Security	CE/2020/70861	07/10/2021	Ni	13770-89-3	0.06%	0.001028547
Solder Ball SnAg1.8		Copper Cu	SDS_Umicore_CU_ 20220621 (Umicore_target_Cu 4N5 2021011	CE/2020/13007	01/17/2021	Copper Cu	7440-50-8	0.08%	0.001387544
TIN. 26210220 TIN. Halicogn. 20 TIN. Halicogn. 2	Solder Ball		SDS_MIT_TS-AG- S- SDS_MIT_TS- S- TIN17 202010	MIT_TS-AG- S_20210220_(S_Halogen_202 S_R2_2021022 Security_C).pdf 10220_(Security_C).pdf	CE/2020/23081 CE/2020/23082	02/20/2021 02/20/2021	Silver	2386-52-9	0.003%	5.42716E-05
** where ND = Not Detectable Total 100.00% 1.76052040			2 20201004 JUH (Security C).par	TIN, 20210220 (Security C), pdf TIN, 2021022 (Security C), pdf TIN, 22 2021022 (Security C), pdf TIN, 22 2021022	CE/2020/23062	02/20/2021	Tin			